



NOTE

All numerical values are in metric units [with U.S. customary units in brackets]. Dimensions are in millimeters. Unless otherwise specified, dimensions have a tolerance of ± 0.13 and angles have a tolerance of $\pm 2^\circ$. Figures are not drawn to scale.

1. INTRODUCTION

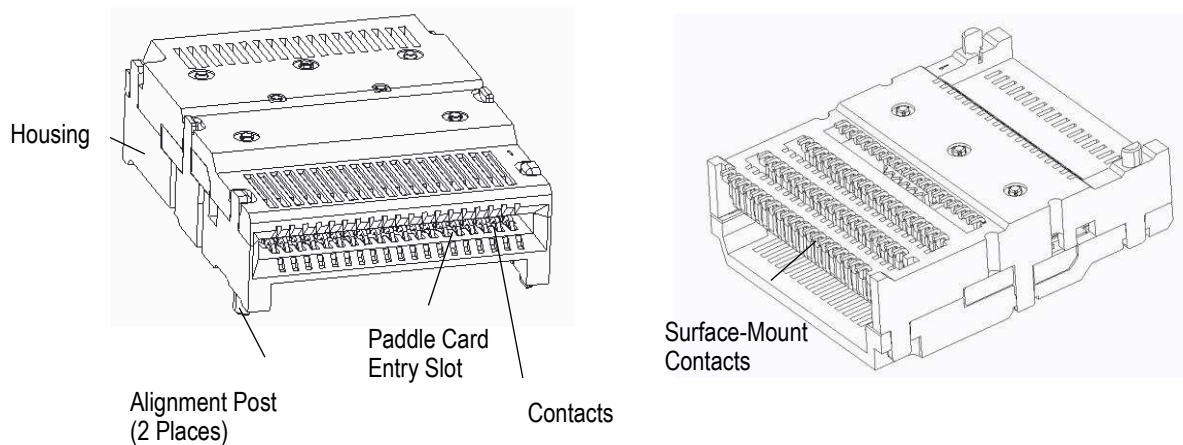
This specification covers the requirements for application of the 76 position QSFP-DD and QSFP-DD 112 PC board connector. The connector consists of a housing with right-angle surface-mount contacts having pitch on 0.8mm centerlines. The connector features a paddle card entry slot that accepts 1.00 ± 0.10 thick integrated circuit card housed in a plug body and alignment posts for stability of placement of the connector on the PC board. The connector is mounted on host PC board and is used on coordination with an EMI cage attached to the same PC board. The cage provides proper alignment to the connector.

The connector is supplied in tape-mounted form for manual or robotic machine placement.

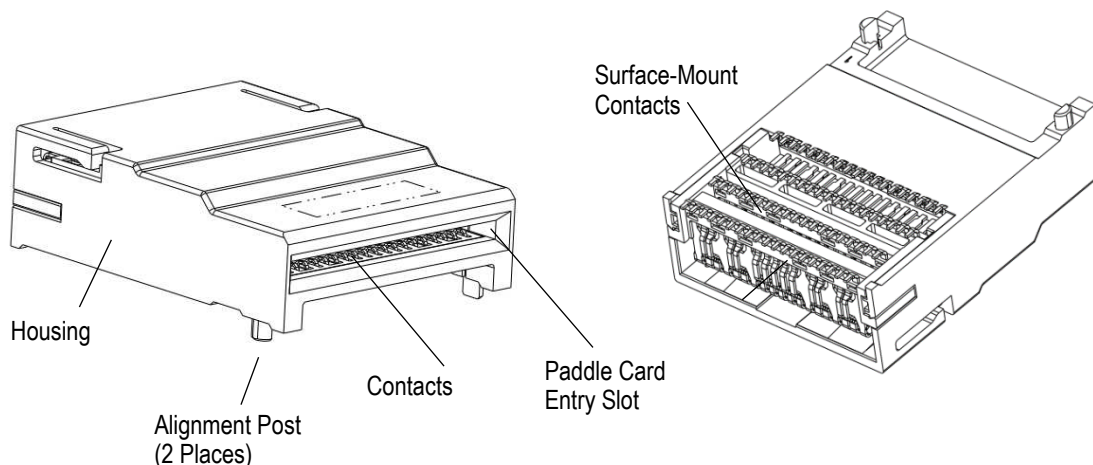
Basic terms and features of this product are provided in Figure 1.

Figure 1

QSFP-DD Connector view



QSFP-DD 112 Connector view



2. REFERENCE MATERIAL

2.1. Revision Summary

Revisions to this application specification include:

- Rev A1: Revised reflow profile, solder paste thickness and stencil recommendation ----03Mar 2021
- Rev B: Added QSFP-DD 112 version to the specification ----15 APR 2021
- Rev B1: Revised solder paste volume----06May 2021

2.2. Customer Assistance

Reference example Product Base Part Numbers 2318579 QSFP-DD (right-angle) and 2372133 QSFP-DD 112 (right angle), and Product Code X011 are representative of 76-position QSFP-DD PC board connectors. Use of these numbers will identify the product line and help you to obtain product and tooling information when visiting www.te.com or calling the number at the bottom of this page.

2.3. Customer Drawings

Customer drawings for product part numbers are available from www.te.com. Information contained in the customer drawing takes priority.

2.4. Manual

Manual [402-40](#) can be used as a guide to soldering. This manual provides information on various flux types and characteristics with the commercial designation and flux removal procedures. A checklist is included in the manual as a guide for information on soldering problems.

2.5. Specifications

Product Specification [108-130016](#) provides expected product performance and test results.

2.6. Instructional Material

Instruction sheets (408-series) provide product assembly instructions or tooling setup and operation procedures. Instructional material that pertains to this product is:

[408-9816](#) Handling Reeled Product

2.7. Standards

The standard that pertains to this product is:

EIA-364-52, "Solderability of Contact Terminations Test Procedure for Electrical Connectors and Sockets"

3. REQUIREMENTS

3.1. Safety

Do not stack product shipping containers so high that the containers buckle or deform.

3.2. Operating Temperature

The connector is designed to operate in a temperature range of -55° to 85°C [-67° to 185°F].

3.3. Material

The housing is made of liquid crystal polymer (LCP) thermoplastic, UL 94-V-0. The contacts are made of copper alloy underplated with nickel, plated with tin on the solder tails, and plated with gold or gold equivalent at the interface area.

3.4. Storage

A. Ultraviolet Light

Prolonged exposure to ultraviolet light may deteriorate the chemical composition used in the product material.

B. Shelf Life

The product should remain in the shipping containers until ready for use to prevent deformation to components. The product should be used on a first in, first out basis to avoid storage contamination that could adversely affect performance.

C. Chemical Exposure

Do not store product near any chemical listed below as they may cause stress corrosion cracking in the material.

Alkalies	Ammonia	Citrates	Phosphates	Citrates	Sulfur Compounds
Amines	Carbonates	Nitrites	Sulfur Nitrites		Tartrates

3.5. PC Board

A. Material and Thickness

The pc board material shall be glass epoxy (FR-4 or G-10). The pc board thickness shall be a minimum of 1.457 mm for single sided application and 2.20 mm minimum for double sided.



NOTE

Call the number at the bottom of page 1 for suitability of other pc board materials.

B. Tolerance

Maximum allowable bow of the board shall be 0.08 over the length of the connector. The coplanarity of the pc board circuit pads must be 0.03.

C. Circuit Pads

The circuit pads must be solderable in accordance with EIA-364-52.

D. Layout

All holes and circuit pads must be precisely located on the pc board. The pc board layout must be designed using the dimensions provided on the customer drawing for the specific connector. A reference sample of the recommended pc board layout is given in Figure 2.

Recommended PC Board Layout for QSFP-DD

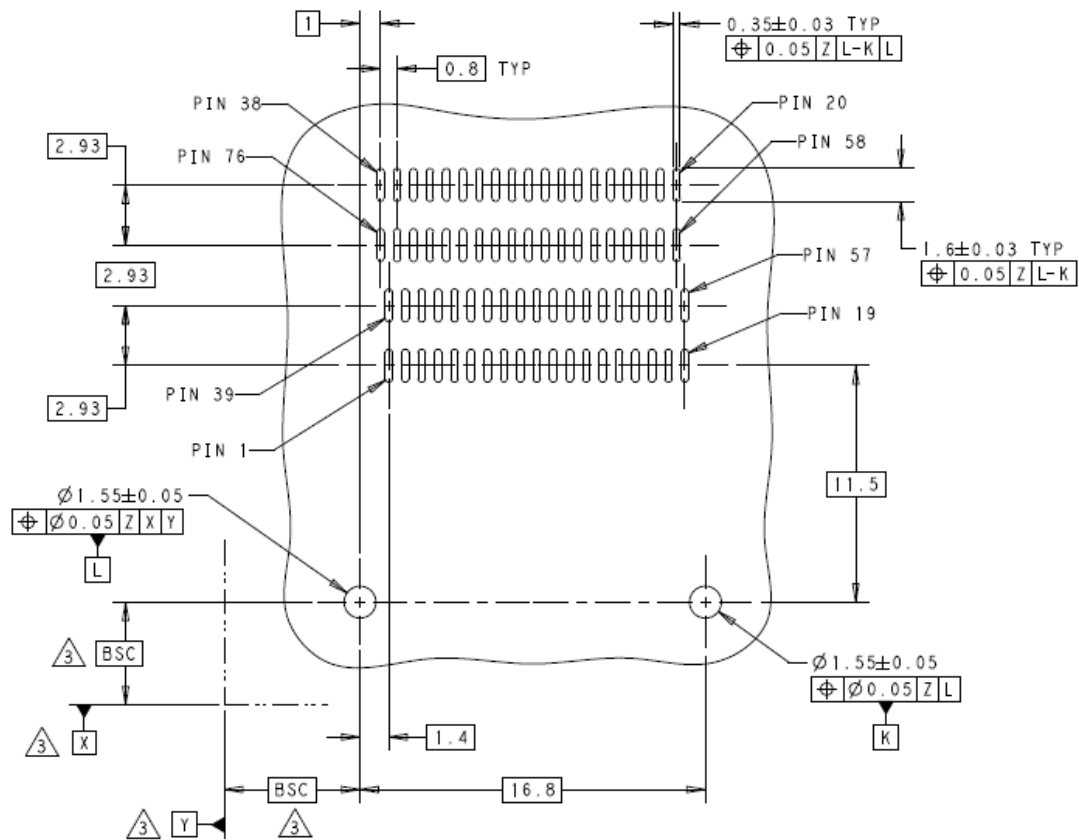


Figure 2

Recommended PC Board Layout for QSFP-DD 112

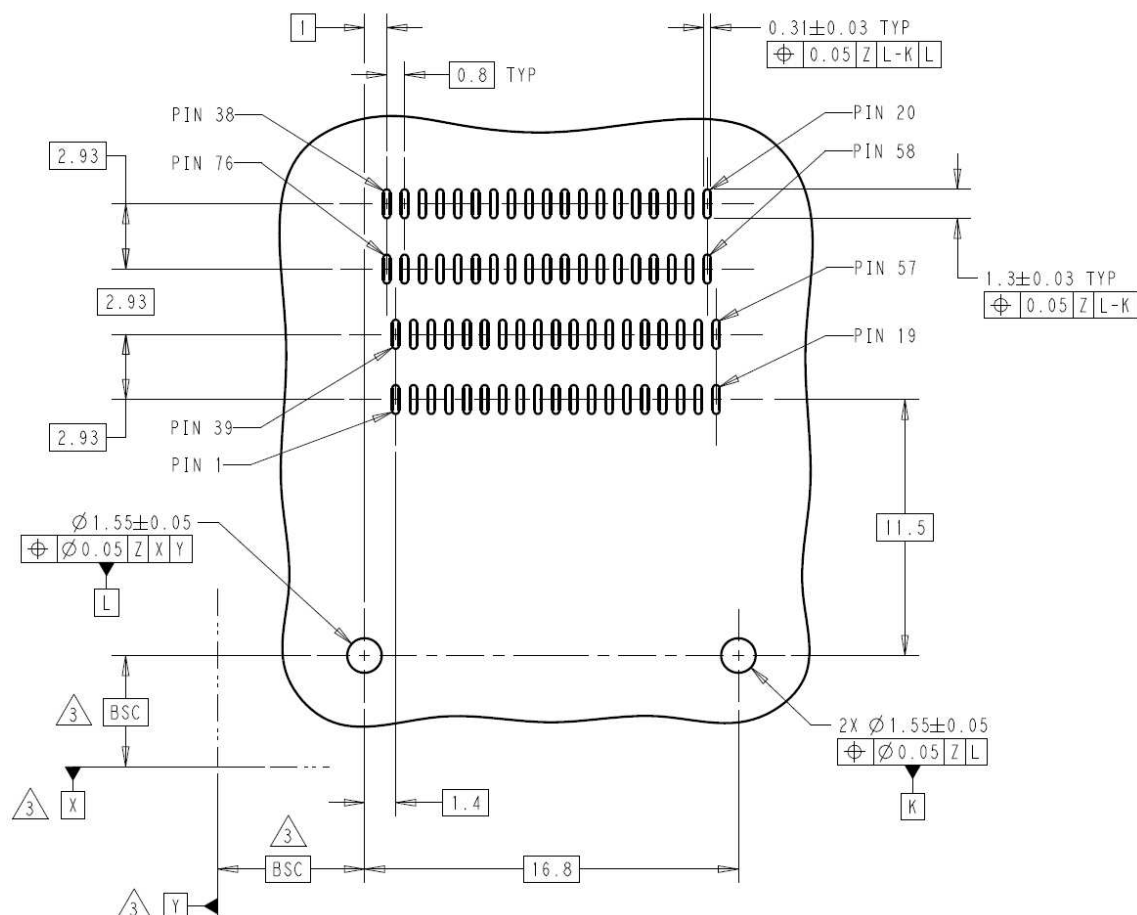


Figure 2 cont'd

3.6. Soldering

A. Process

The connector must be soldered using non-focused infrared (IR) reflow or equivalent soldering technique. Reflow temperature and time may vary depending on the size of the pc board and placement of other components. This connector can be subjected to the reflow temperature and approximate time specified in Figure 3.

B. Solder Paste Characteristics

1. Alloy type for tin-lead solder shall be 63 Sn/37 Pb, 60 Sn/40 Pb, or 62 Sn/36 Pb/2 Ag.
2. Alloy type for lead-free solder shall be compatible with pure tin or gold, for example, SAC305 (96.6 Sn/3 Ag/0.5 Cu) or SAC405 (95.5 Sn/4 Ag/0.5 Cu)
3. Flux incorporated in the paste shall be rosin, mildly active (RMA) type.
4. Paste will be at least 80% solids by volume.
5. Mesh designation shall be -200 to +325 (74 to 44 square micron openings, respectively).

6. Minimum viscosity of screen print shall be $5 \times 10\%$ cp (centipoise).
7. Minimum viscosity of stencil print shall be $7.5 \times 10\%$ cp (centipoise).

C. Solder Volume

Minimum solder volume (V) (before curing) for each circuit pad is calculated as follows:

QSFP-DD: $1.6(\text{pad length}) \times 130\% \times 0.35(\text{pad width}) \times 0.13(\text{Solder Paste thickness}) = 0.095 \text{ mm}^3 (V)$.

QSFP-DD112: $1.3(\text{pad length}) \times 170\% \times 0.31(\text{pad width}) \times 0.13(\text{Solder Paste thickness}) = 0.089 \text{ mm}^3 (V)$.

Customer can adjust the solder volume for best solderability.



NOTE

Solder volume may vary depending on solder paste composition.

D. Solder Paste Thickness

Solder paste thickness for the connector contact solder tines should be at least 0.13mm. Customer can increase thickness as needed in their manufacture to improve solderability, but no soldering bridge is allowed between adjacent tails.

E. Stencil

The stencil thickness should be determined by specified solder paste thickness, and its apertures' size are recommended to be with same width as circuit pad, but at least 130% longer towards to single rear direction. Customer can also adjust according to different solder paste characteristic.

The stencil should include circuit pads for the contacts and holes for the stabilizers and hold-downs. The stencil layout must be designed base on the dimensions provided on the customer drawing for the specific connector

F. Solder Mask

When soldering, solder mask is recommended between all circuit pads to minimize solder bridging between pads. The mask must not exceed the height of the pad. If a trace is run between adjacent pads on the pc board, a solder mask must be applied over the trace to prevent bridging and wicking of solder away from the connector contact solder tines. Mask most suitable is Liquid Photo Imageable.

It is recommended that component temperatures not exceed the temperatures and times given in Figure 3.


CAUTION

Excessive temperatures may cause connector housing degradation or plating deterioration.

Reflow Soldering Profiles

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate ($T_{s_{max}}$ to T_p)	3° C/second max.
Preheat	
Temperature Min ($T_{s_{min}}$)	150 °C
Temperature Max ($T_{s_{max}}$)	200 °C
Time ($t_{s_{min}}$ to $t_{s_{max}}$)	60-180 seconds
Time maintained above: Temperature (T_L)	217 °C
Time (t_L)	30-90 seconds
Peak/Classification Temperature (T_p)	230°C ~250°C
Time within 5 °C of actual Peak Temperature (t_p)	20-40 seconds
Ramp-Down Rate	6 °C/second max.
Time 25 °C to Peak Temperature	8 minutes max.

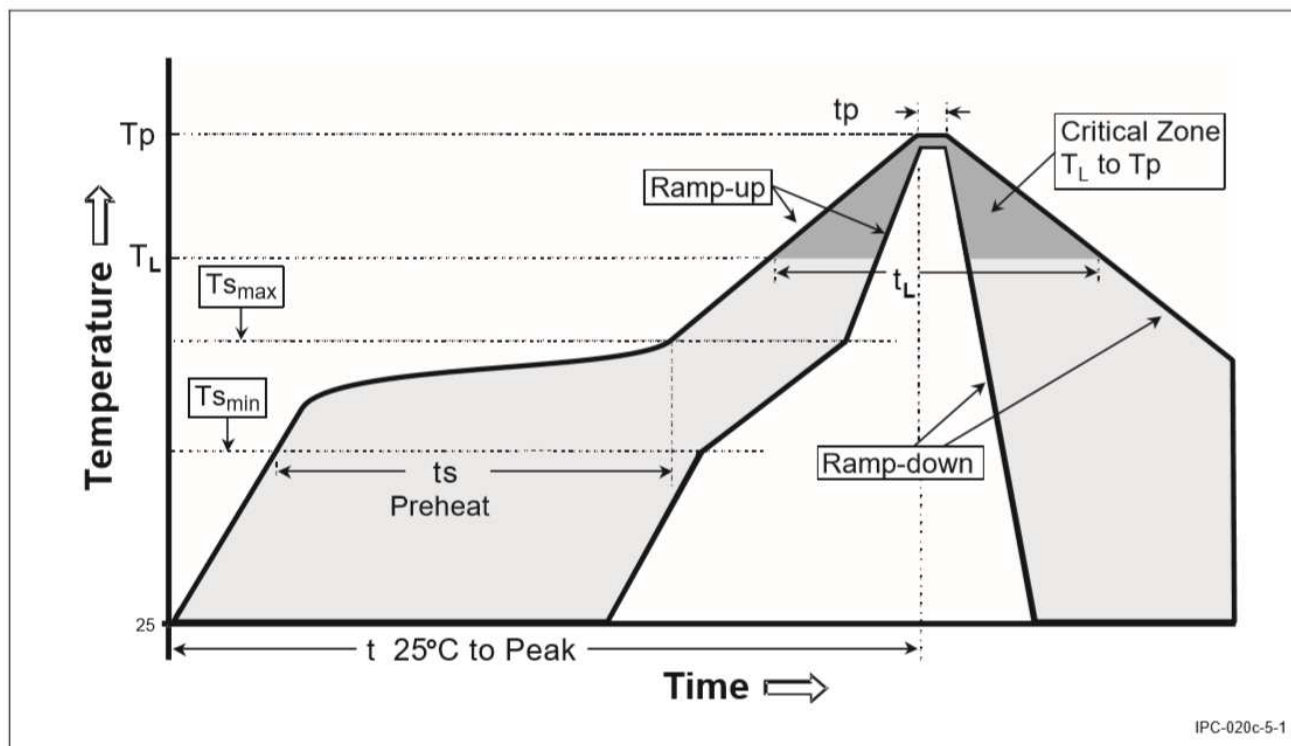


Figure 3

G. Cleaning

After soldering, removal of fluxes, residues, and activators is necessary. Consult with the supplier of the solder and flux for recommended cleaning solvents. Cleaners must be free of dissolved flux and other contaminants. It is recommended cleaning the pc board on its edge. If using aqueous cleaner, standard equipment such as a soak-tank or an automatic in-line machine should be used. Common cleaning solvents that will not affect this connector are listed in Figure 4.



DANGER

Consideration must be given to toxicity and other safety requirements recommended by the solvent manufacturer. Refer to the manufacturer's material safety data sheet (MSDS) for characteristics and handling of cleaners. Trichloroethylene and methylene chloride is not recommended because of harmful occupational and environmental effects.

CLEANER		TIME (Minutes)	TEMPERATURE (Max)
NAME	TYPE		
ALPHA 2110	Aqueous	1	132°C [270°F]
BIOACT EC-7	Solvent	5	100°C [212°F]
Butyl CARBITOL	Solvent	1	Ambient Room
Isopropyl Alcohol	Solvent	5	100°C [212°F]
KESTER 5778	Aqueous		
KESTER 5779	Aqueous		
LONCOTERGE 520	Aqueous		
LONCOTERGE 530	Aqueous		
Terpene	Solvent		

Figure 4



NOTE

If a cleaning solvent is not listed, call the number at the bottom of page 1 for advice.

H. Drying

When drying cleaned assemblies and pc boards, temperature limitations must not be exceeded: 85°C [185°F]. Excessive temperatures may cause connector housing degradation.

3.7. Connector Placement



CAUTION

Connectors should be handled only by the housing to avoid deformation, contamination, or damage to the contact solder tines.

Each contact solder tine must be seated on its pc board circuit pad. Optimally, the tines should be centered on the pc board circuit pads; however, slight misalignment is permissible.

Because the connector alignment posts are for clearance and fit only, the force required to seat the connector is minimal. The alignment posts must be inserted into the pc board holes.

3.8. Checking Installed Connector

All solder joints must conform to the requirements specified in Workmanship Specification [101-21](#) and all other requirements specified in this document. The solder fillets must be evenly formed around each contact solder tine. Solder must have 95% minimum coverage over the circuit pad.

3.9. Removal and Repair

Standard de-soldering methods must be used to remove the connector from the pc board. The connector must not be re-used after removal. The connector is not repairable. Defective or damaged product must not be used.

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4. QUALIFICATION

QSFP_DD pc board connectors are Recognized by Underwriters Laboratories Inc. (UL) in File E28476.

5. TOOLING

No tooling is required for manual placement of the connectors onto the pc board.

For automatic machine placement, the robotic equipment must have a true position accuracy tolerance sufficient to properly locate the connector. This includes gripper and fixture tolerances as well as equipment repeatability. It must use the connector datum surfaces given on the customer drawing to ensure reliable placement.

6. VISUAL AID

RIGHT-ANGLE CONNECTOR

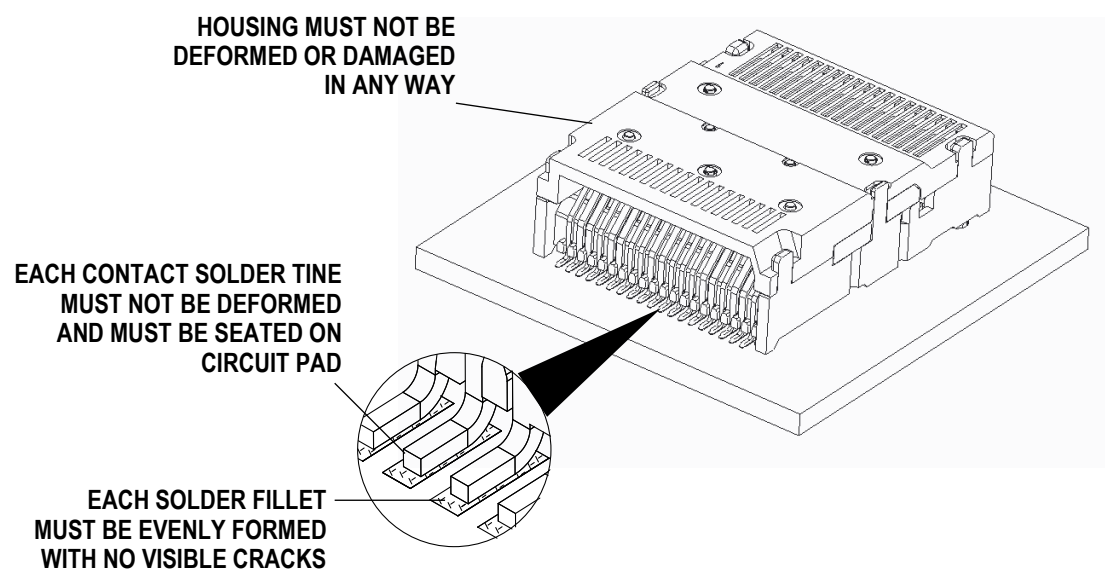


Figure 5. Visual Aid

The illustration above shows a typical application of 76-position QSFP_DD pc board connector. This illustration should be used by production personnel to ensure a correctly applied product. Applications which do not appear correct should be inspected using the information in the preceding pages of this specification and in the instructional material shipped with the product or tooling.